

Smart Highside Power Switch

Reversave™

- Reverse battery protection by self turn on of power MOSFET

Features

- Short circuit protection
- Current limitation
- Overload protection
- Thermal shutdown
- Overvoltage protection (including load dump)
- Loss of ground protection
- Loss of V_{bb} protection (with external diode for charged inductive loads)
- Very low standby current
- Fast demagnetisation of inductive loads
- Electrostatic discharge (ESD) protection
- Optimized static electromagnetic compatibility (EMC)

Diagnostic Function

- Proportional load current sense (with defined fault signal while thermal shutdown)

Application

- Power switch with current sense diagnostic feedback for 12V and 24 V DC grounded loads
- All types of resistive, capacitive and inductive loads (no PWM with inductive loads)
- Replaces electromechanical relays, fuses and discrete circuits

General Description

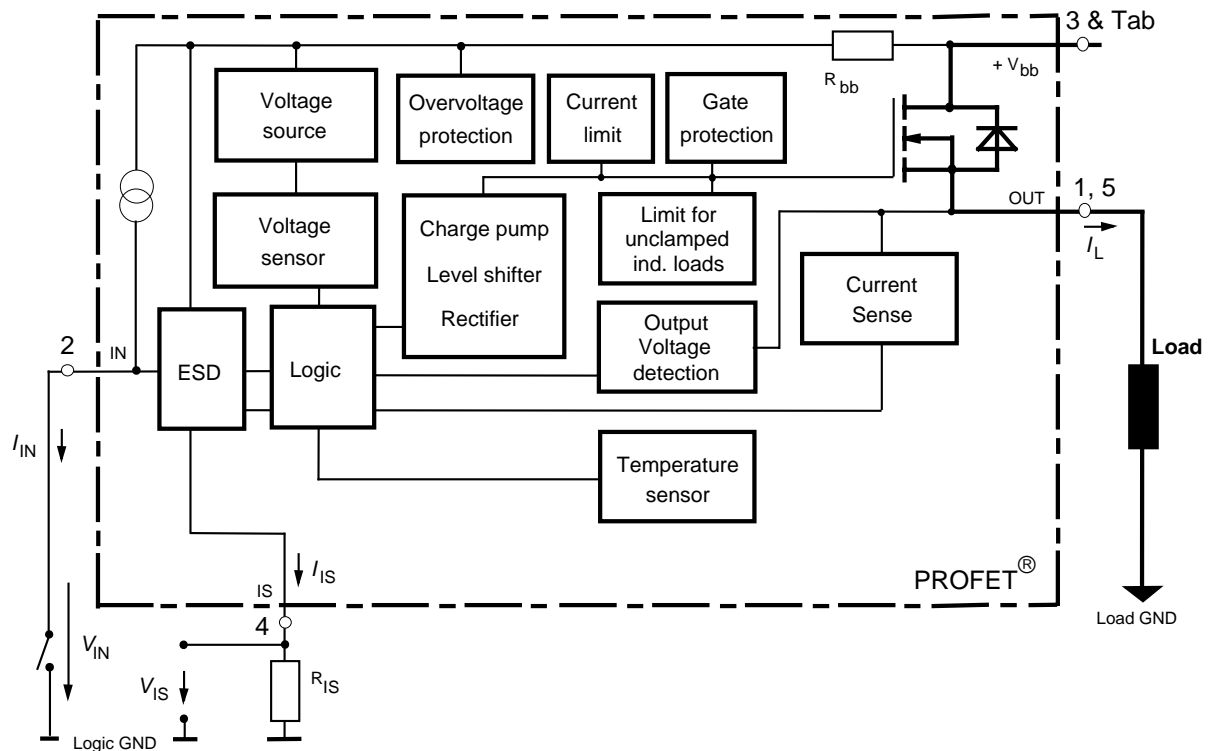
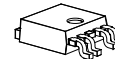
N channel vertical power FET with charge pump, current controlled input and diagnostic feedback with load current sense, integrated in Smart SIPMOS® chip on chip technology. Fully protected by embedded protection functions.

Product Summary

Operating voltage	$V_{bb(on)}$	5.0 ... 36	V
On-state resistance	R_{ON}	16	mΩ
Load current (ISO)	$I_L(ISO)$	25	A
Current limitation	$I_L(SCr)$	65	A

Package

TO-252-5-1
(DPAK 5 pin; less than half the size as TO 220 SMD)



Pin	Symbol		Function
1	OUT	O	Output to the load. The pin 1 and 5 must be shorted with each other especially in high current applications!*)
2	IN	I	Input, activates the power switch in case of short to ground
Tab/(3)	V _{bb}	+	Positive power supply voltage, the tab is shorted to this pin.
4	IS	S	Diagnostic feedback providing a sense current proportional to the load current; high current on failure (see Truth Table)
5	OUT	O	Output to the load. The pin 1 and 5 must be shorted with each other especially in high current applications!*)

*) Not shorting all outputs will considerably increase the on-state resistance, reduce the peak current capability and decrease the current sense accuracy

Maximum Ratings at $T_j = 25\text{ °C}$ unless otherwise specified

Parameter	Symbol	Values	Unit
Supply voltage (overvoltage protection see page 4)	V_{bb}	36	V
Supply voltage for full short circuit protection (see also diagram on page 9) $T_j = -40 \dots 150\text{ °C}$:	V_{bb}	24 ¹⁾	V
Load dump protection $V_{LoadDump} = U_A + V_s$, $U_A = 13.5\text{ V}$ $R_I = 2\ \Omega$, $R_L = 2.7\ \Omega$, $t_d = 200\text{ ms}$, IN= low or high	$V_{Load\ dump}^{2)}$	60	V
Load current (Short-circuit current, see page 4)	I_L	self-limited	A
Operating temperature range	T_j	-40 ... +150	°C
Storage temperature range	T_{stg}	-55 ... +150	
Power dissipation (DC) $TC \leq 25\text{ °C}$	P_{tot}	42	W
Inductive load switch-off energy dissipation, single pulse $U=12\text{V}$, $I=10\text{A}$, $L=3\text{mH}$ $T_j=150\text{ °C}$:	E_{AS}	0.15	J
Electrostatic discharge capability (ESD) (Human Body Model) acc. ESD assn. std. S5.1-1993; $R=1.5\text{k}\Omega$; $C=100\text{pF}$	V_{ESD}	4.0	kV
Current through input pin (DC)	I_{IN}	+15, -100	mA
Current through current sense pin (DC) see internal circuit diagrams page 7	I_{IS}	+15, -100	

1) Short circuit is tested with $100\text{m}\Omega$ and $20\mu\text{H}$

2) $V_{Load\ dump}$ is set-up without the DUT connected to the generator per ISO 7637-1 and DIN 40839

Thermal Characteristics

Parameter and Conditions	Symbol	Values			Unit
		min	typ	max	
Thermal resistance chip - case: junction - ambient (free air): SMD version, device on PCB ⁴ :	$R_{thJC}^{3)}$	--	--	1.5	K/W
	R_{thJA}	--	80	--	
				45	

Electrical Characteristics

Parameter and Conditions at $T_j = -40^\circ\text{C} \dots 150^\circ\text{C}$, $V_{bb} = 12\text{ V}$ unless otherwise specified	Symbol	Values			Unit
		min	typ	max	

Load Switching Capabilities and Characteristics

On-state resistance (pin 3 to pin 1,5) $V_{IN} = 0$, $I_L = 5\text{ A}$	R_{ON}	--	$T_j = 25^\circ\text{C}$: 13	16	m Ω
$T_j = 150^\circ\text{C}$:			25	31	
Output voltage drop limitation at small load currents (Tab to pin 1,5) $T_j = -40 \dots 150^\circ\text{C}$:	$V_{ON(NL)}$	--	50	--	mV
Nominal load current (Tab to pin 1,5) ISO Proposal: $V_{ON} = 0.5\text{ V}$, $T_C = 85^\circ\text{C}$	$I_{L(ISO)}$	21	25	--	A
Turn-on time to 90% V_{OUT} :	t_{on}	150	--	410	μs
Turn-off time to 10% V_{OUT} :	t_{off}	70	--	410	
$R_L = 2,5\Omega$, $T_j = -40 \dots 150^\circ\text{C}$					
Slew rate on 10 to 30% V_{OUT} , $R_L = 2.5\ \Omega$, $T_j = -40 \dots 150^\circ\text{C}$	dV/dt_{on}	0.1	--	1	V/ μs
Slew rate off 70 to 40% V_{OUT} , $R_L = 2.5\ \Omega$, $T_j = -40 \dots 150^\circ\text{C}$	$-dV/dt_{off}$	0.1	--	1	V/ μs

³⁾ Thermal resistance R_{thCH} case to heatsink (about 0.5 ... 0.9 K/W with silicone paste) not included!

⁴⁾ Device on 50mm*50mm*1.5mm epoxy PCB FR4 with 6cm² (one layer, 70 μm thick) copper area for V_{bb} connection. PCB is vertical without blown air.

Parameter and Conditions at $T_j = -40^\circ\text{C} \dots 150^\circ\text{C}$, $V_{bb} = 12\text{ V}$ unless otherwise specified	Symbol	Values			Unit
		min	typ	max	

Operating Parameters

Operating voltage ($V_{IN}=0$)	$V_{bb(on)}$	5.0	--	36	V	
Undervoltage shutdown ⁵⁾	$V_{bIN(u)}$	1.5	3.0	4.5	V	
Undervoltage restart of charge pump	$V_{bb(ucp)}$	3.0	4.5	6.0	V	
Overvoltage protection ⁶⁾ $I_{bb}=15\text{ mA}$	$V_{Z,IN}$	61	68	--	V	
Standby current $I_{IN}=0$	$T_j=-40\dots+25^\circ\text{C}$: $T_j=150^\circ\text{C}$:	$I_{bb(off)}$	-- --	2 4	5 8	μA

Protection Functions

Short circuit current limit (Tab to pin 1,5) $V_{ON} = 12\text{V}$, time until limitation max. 300 μs $T_j = -40^\circ\text{C}$: $T_j = 25^\circ\text{C}$: $T_j = +150^\circ\text{C}$:	$I_{L(SC)}$	35 35 35	75 65 65	110 110 125	A
Repetitive short circuit current limit, $T_j = T_{jt}$	$I_{L(SCr)}$	--	65	--	A
Output clamp (inductive load switch off) at $V_{OUT} = V_{bb} - V_{ON(CL)}$ (e.g. overvoltage) $I_L = 40\text{ mA}$ ⁷⁾	$V_{ON(CL)}$	38	42	48	V
Thermal overload trip temperature	T_{jt}	150	--	--	$^\circ\text{C}$
Thermal hysteresis	ΔT_{jt}	--	10	--	K

Reverse Battery

Reverse battery voltage	$-V_{bb}$	--	--	20	V
On-state resistance (pin 1,5 to pin 3) $V_{bb} = -8\text{V}$, $V_{IN} = 0$, $I_L = -5\text{ A}$, $R_{IS} = 1\text{ k}\Omega$, $T_j = 25^\circ\text{C}$: $V_{bb} = -12\text{V}$, $V_{IN} = 0$, $I_L = -5\text{ A}$, $R_{IS} = 1\text{ k}\Omega$, $T_j = 25^\circ\text{C}$: $T_j = 150^\circ\text{C}$:	$R_{ON(rev)}$	-- --	-- 16 25	22 19 32	$\text{m}\Omega$
Integrated resistor in V_{bb} line	R_{bb}	--	200	--	Ω

5) $V_{bIN} = V_{bb} - V_{IN}$ see diagram page 11.

6) see also $V_{ON(CL)}$ in circuit diagram page 7.

7) see also page 9

Parameter and Conditions at $T_j = -40^\circ\text{C} \dots 150^\circ\text{C}$, $V_{bb} = 12\text{ V}$ unless otherwise specified	Symbol	Values			Unit
		min	typ	max	

Diagnostic Characteristics

Current sense ratio, static on-condition $k_{ILIS} = I_L : I_{IS}$, $V_{ON} < 1.5\text{ V}^8)$, $V_{IS} < V_{OUT} - 5\text{ V}$, $V_{bIN} > 4.5\text{ V}$	k_{ILIS}	--	8200	--	
IL = 20A, $T_j = -40^\circ\text{C}$:		7400	8300	9100	
$T_j = +25^\circ\text{C}$:		7500	8300	9100	
$T_j = +150^\circ\text{C}$:		7500	8200	8800	
IL = 5A, $T_j = -40^\circ\text{C}$:		6800	8300	9700	
$T_j = +25^\circ\text{C}$:		7200	8300	9300	
$T_j = +150^\circ\text{C}$:		7200	8200	9000	
IL = 2.5A, $T_j = -40^\circ\text{C}$:		6800	8500	10000	
$T_j = +25^\circ\text{C}$:		6800	8500	9800	
$T_j = +150^\circ\text{C}$:		6800	8100	9200	
IL = 1A, $T_j = -40^\circ\text{C}$:		6800	8600	10500	
$T_j = +25^\circ\text{C}$:		6800	8600	10500	
$T_j = +150^\circ\text{C}$:		6800	8600	10500	
$I_{IN} = 0$ (e.g. during deenergising of inductive loads):		--	n.a.	--	
Sense current under fault conditions; $V_{DS} > 1.5\text{ V}$, typ. $T_j = -40 \dots +150^\circ\text{C}$:	$I_{IS, \text{fault}}$	2.5	4	--	mA
Fault-Sense signal delay after negative input slope	$t_{\text{delay}(\text{fault})}$			0.8	ms
Current sense leakage current $I_{IN} = 0$; $V_{IN} = 0$, $I_L = 0$:	$I_{IS(\text{LL})}$ $I_{IS(\text{LH})}$	--	--	0.5	μA
		--	4	12	
Current sense settling time to $I_{IS \text{ static}} \pm 10\%$ after positive input slope, $I_L = 0$ — 20 A, $T_j = -40 \dots +150^\circ\text{C}$ (not tested, specified by design)	$t_{\text{son}(IS)}$	--	--	400	μs
Overvoltage protection $I_{bb} = 15\text{ mA}$ $T_j = -40 \dots +150^\circ\text{C}$:	$V_{bIS(Z)}$	61	68	--	V

Input

Required current capability of input switch $T_j = -40 \dots +150^\circ\text{C}$:	$I_{IN(\text{on})}$	--	0.7	1.2	mA
Maximum input current for turn-off $T_j = -40 \dots +150^\circ\text{C}$:	$I_{IN(\text{off})}$	--	--	50	μA

⁸⁾ If V_{ON} is higher, the sense current is no longer proportional to the load current due to sense current saturation, see $I_{IS, \text{lim}}$.

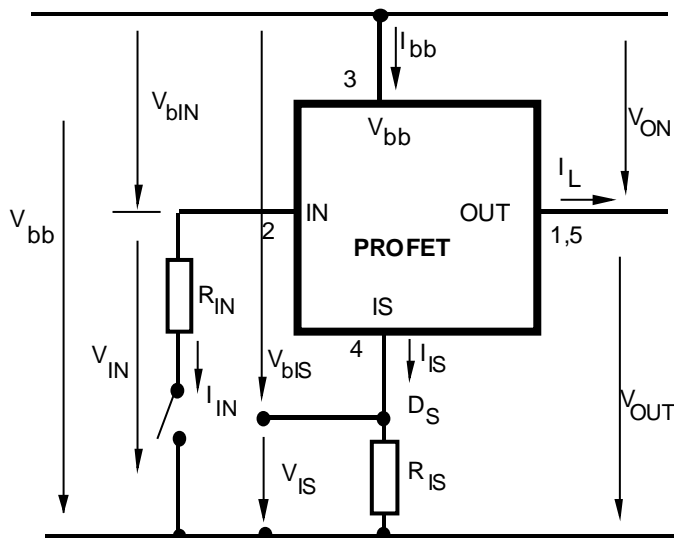
Truth Table

	Input Current level	Output level	Current Sense I_{IS}
Normal operation	L	L	0
	H	H	nominal
Overload	L	L	0
	H	H	$I_{ISfault}$
Short circuit to GND	L	L	0
	H	L	$I_{ISfault}$
Overtemperature	L	L	0
	H	L	$I_{ISfault}$
Short circuit to V_{bb}	L	H	0
	H	H	<nominal ⁹
Open load	L	Z	0
	H	H	0

L = "Low" Level
H = "High" Level

Z = high impedance, potential depends on external circuit

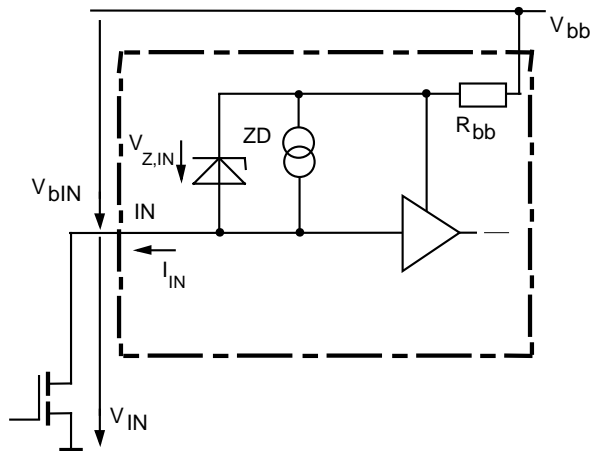
Terms



Two or more devices can easily be connected in parallel to increase load current capability.

⁹⁾ Low ohmic short to V_{bb} may reduce the output current I_L and therefore also the sense current I_{IS} .

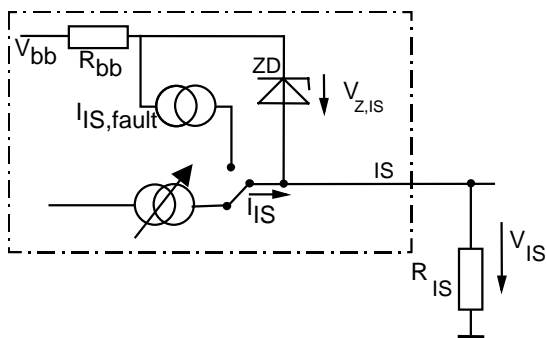
Input circuit (ESD protection)



ESD-Zener diode: 68 V typ., max 15 mA;

Current sense output

Normal operation

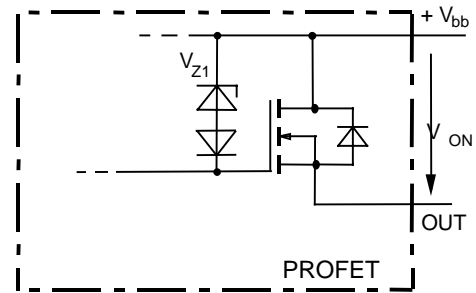


$V_{Z,IS} = 68\text{V}$ (typ.), $R_{IS} = 1\text{ k}\Omega$ nominal (or $1\text{ k}\Omega/n$, if n devices are connected in parallel). $I_S = I_L/K_{ilis}$ can be only driven by the internal circuit as long as $V_{out} - V_{IS} > 5\text{V}$. If you want to measure load currents

up to $I_{L(M)}$, R_{IS} should be less than $\frac{V_{bb} - 5\text{V}}{I_{L(M)} / K_{ilis}}$.

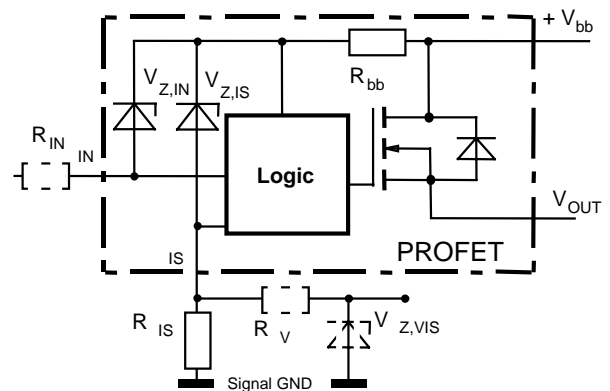
Note: For large values of R_{IS} the voltage V_{IS} can reach almost V_{bb} . See also overvoltage protection. If you don't use the current sense output in your application, you can leave it open.

Inductive and overvoltage output clamp



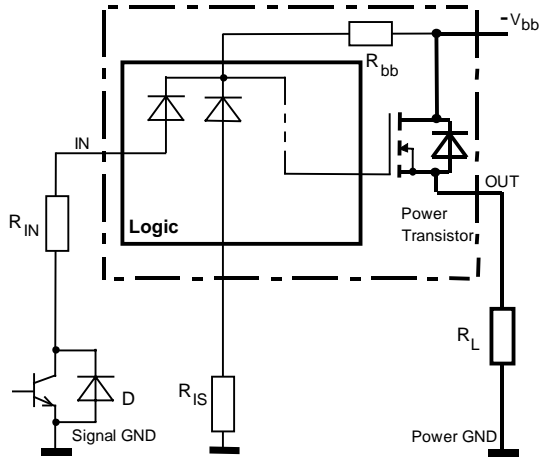
V_{ON} is clamped to $V_{ON(CI)} = 42\text{V}$ typ

Overvoltage protection of logic part



$R_{bb} = 200\Omega$ typ., $V_{Z,IN} = V_{Z,IS} = 68\text{V}$ typ., $R_{IS} = 1\text{ k}\Omega$ nominal. Note that when overvoltage exceeds 73V typ. a voltage above 5V can occur between IS and GND , if R_V , $V_{Z,VIS}$ are not used.

Reversave™ (Reverse battery protection)



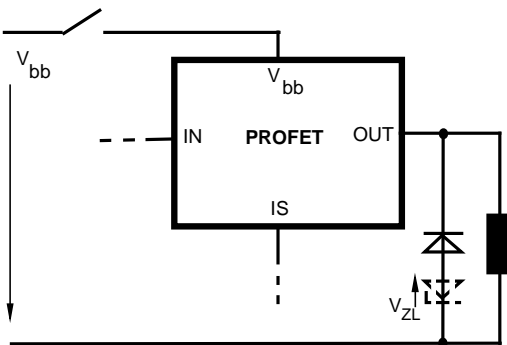
$R_V \geq 1k\Omega$, $R_{IS} = 1k\Omega$ nominal. Add R_{IN} for reverse battery protection in applications with V_{bb} above 16V;
 recommended value: $\frac{1}{R_{IN}} + \frac{1}{R_{IS}} + \frac{1}{R_V} = \frac{0.05A}{|V_{bb}|-12V}$

To minimise power dissipation at reverse battery operation, the summarised current into the IN and IS pin should be about 50mA. The current can be provided by using a small signal diode D in parallel to the input switch, by using a MOSFET input switch or by proper adjusting the current through R_{IS} and R_V .

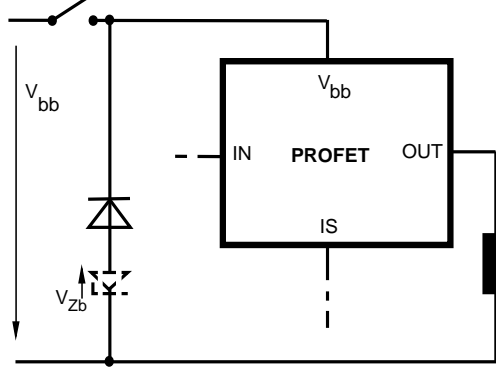
V_{bb} disconnect with energised inductive load

Provide a current path with load current capability by using a diode, a Z-diode, or a varistor. ($V_{ZL} < 73V$ or $V_{Zb} < 30V$ if $R_{IN}=0$). For higher clamp voltages currents at IN and IS have to be limited to 250 mA.

Version a:

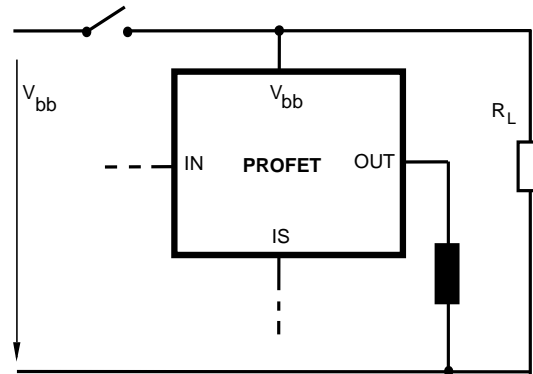


Version b:

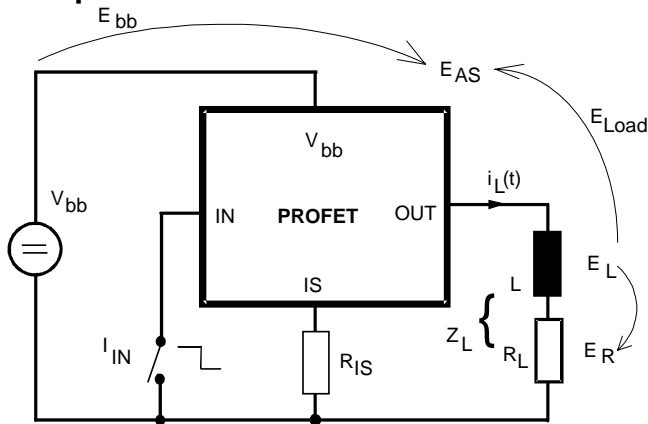


Note that there is no reverse battery protection when using a diode without additional Z-diode V_{ZL} , V_{Zb} .

Version c: Sometimes a necessary voltage clamp is given by non inductive loads R_L connected to the same switch and eliminates the need of clamping circuit:



Inductive load switch-off energy dissipation



Energy stored in load inductance:

$$E_L = 1/2 \cdot L \cdot I_L^2$$

While demagnetising load inductance, the energy dissipated in PROFET is

$$E_{AS} = E_{bb} + E_L - E_R = \int V_{ON(CL)} \cdot i_L(t) dt,$$

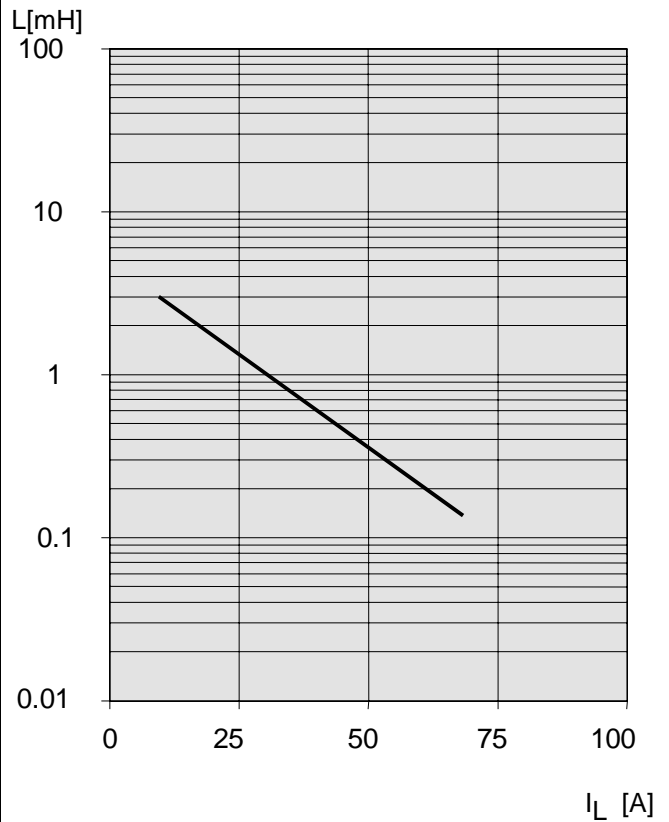
with an approximate solution for $R_L > 0 \Omega$:

$$E_{AS} = \frac{I_L \cdot L}{2 \cdot R_L} (V_{bb} + |V_{OUT(CL)}|) \ln \left(1 + \frac{I_L \cdot R_L}{|V_{OUT(CL)}|} \right)$$

The device is not suitable for permanent PWM with inductive loads if active clamping occurs every cycle.

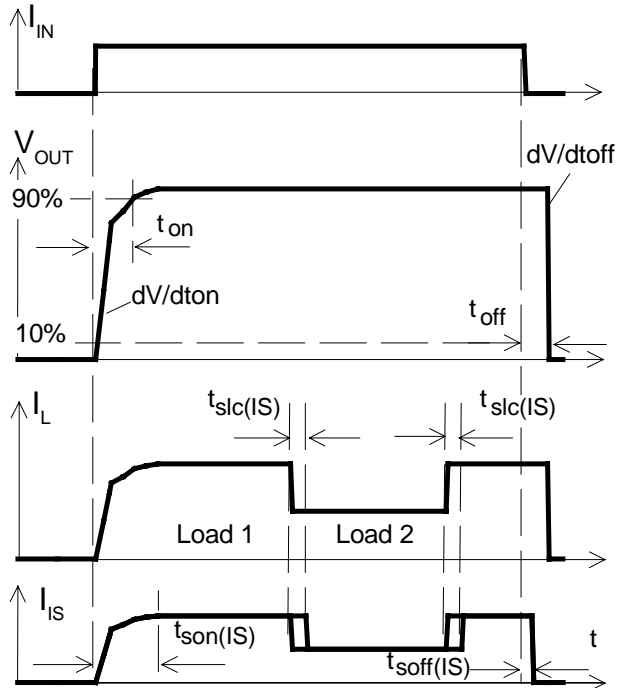
Maximum allowable load inductance for a single switch off

$L = f(I_L)$; $T_{j,start} = 150^\circ C$, $V_{bb} = 12 V$, $R_L = 0 \Omega$



Timing diagrams

Figure 1a: Switching a resistive load, change of load current in on-condition:



The sense signal is not valid during a settling time after turn-on/off and after change of load current.

Figure 1b: typical behaviour of sense output:

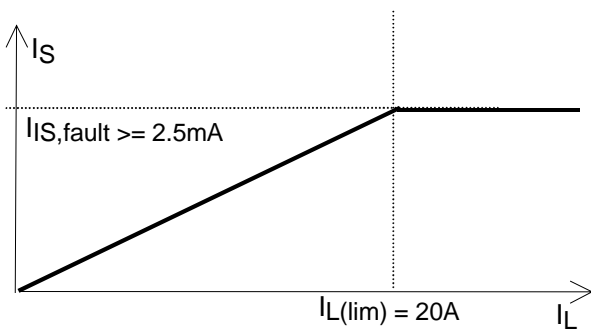
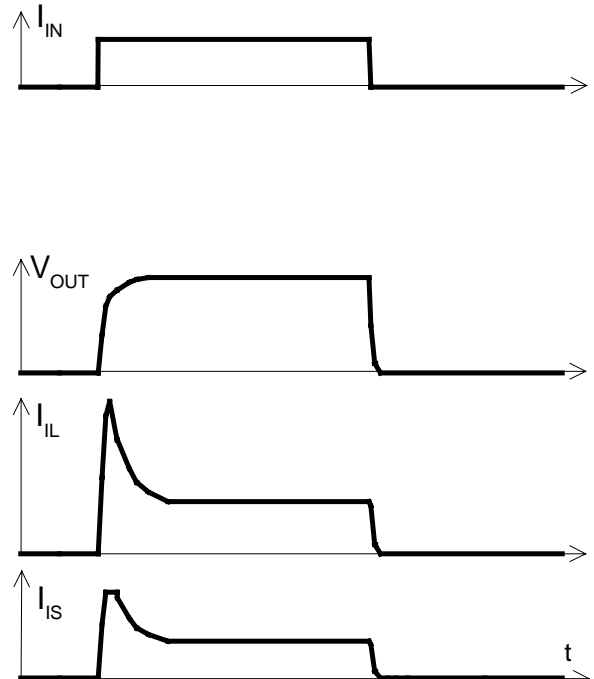


Figure 2a: Switching motors and lamps:



Sense current above $I_{IS, fault}$ can occur at very high inrush currents.

Figure 2b: Switching an inductive load:

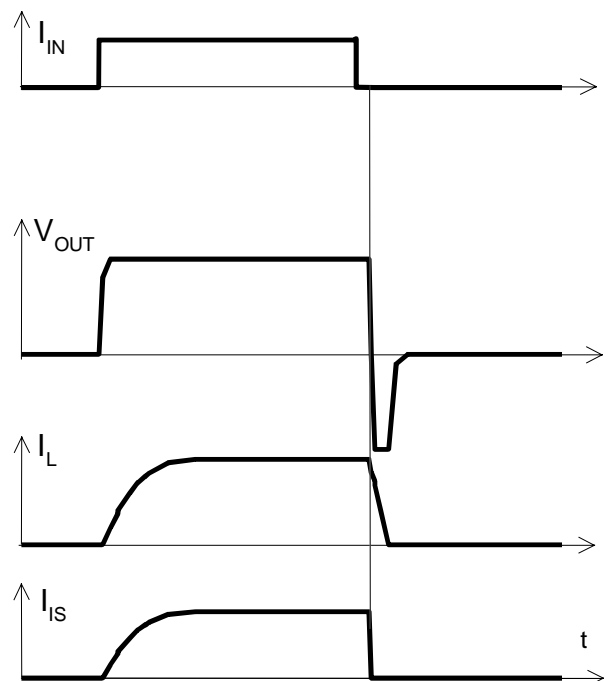


Figure 3a: Short circuit:

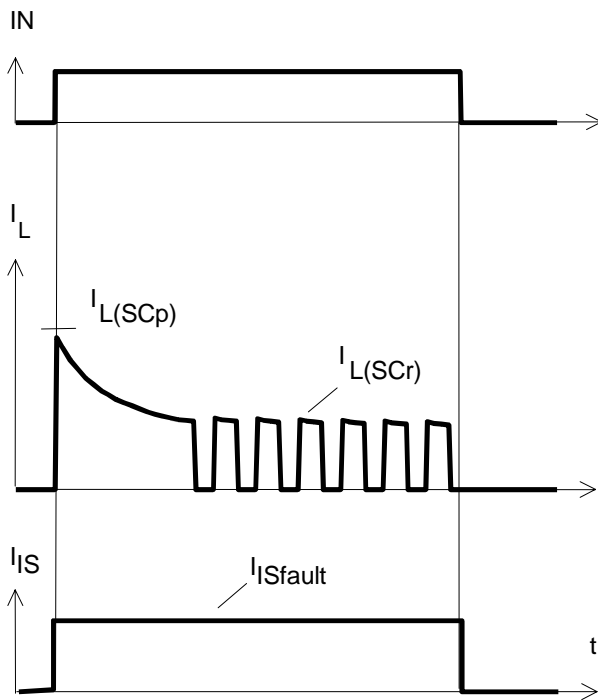


Figure 4a: Overtemperature Reset if $T_j < T_{jt}$

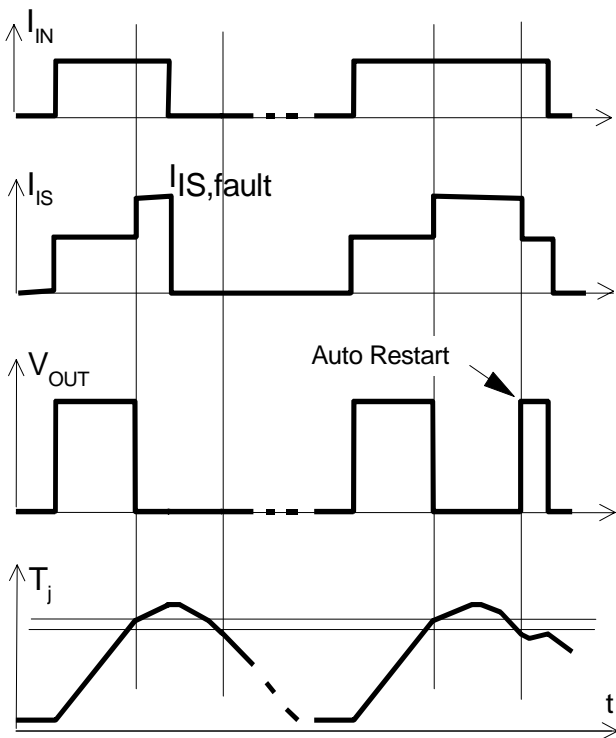


Figure 5a: Undervoltage restart of charge pump, overvoltage clamp

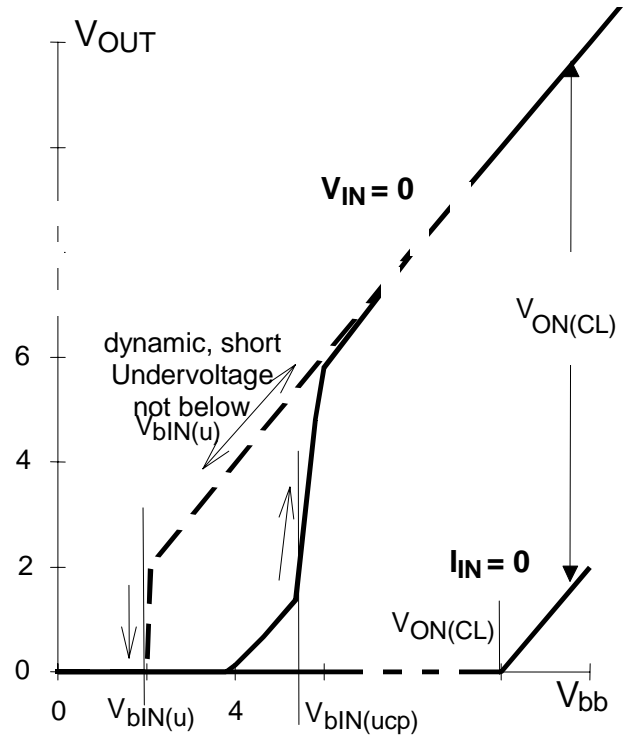


Figure 6a: Current sense versus load current:

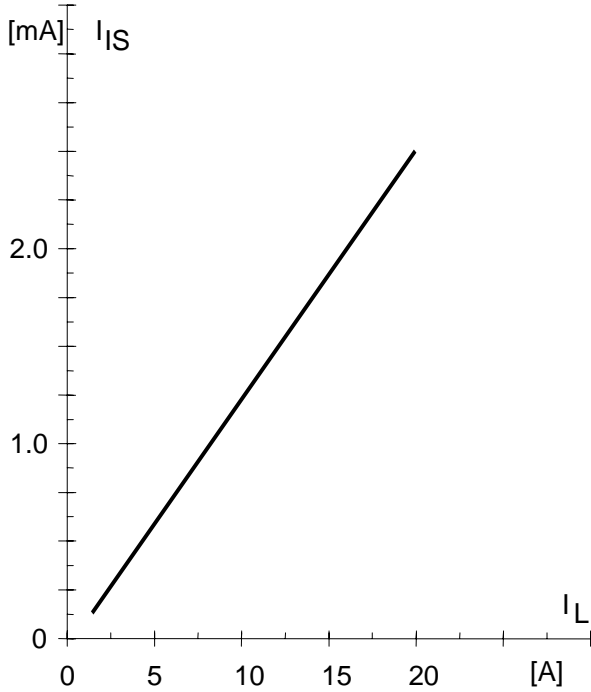


Figure 6b: Current sense ratio¹⁰:

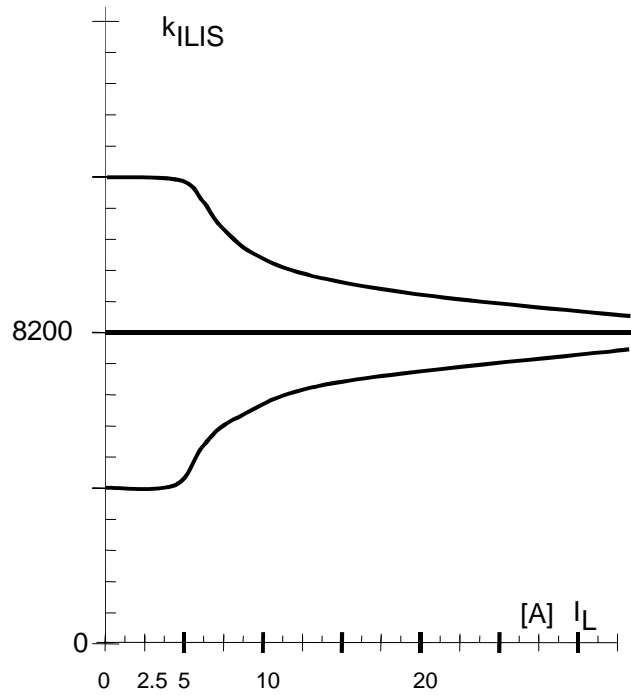
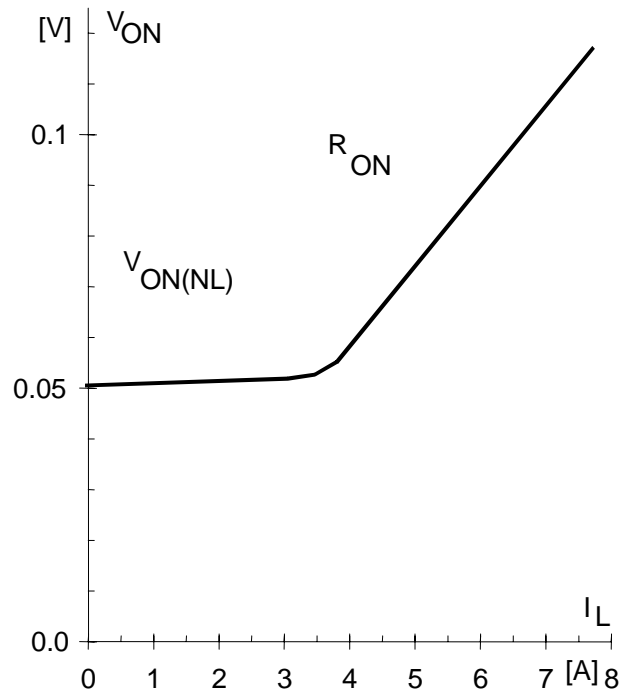


Figure 7a: Output voltage drop versus load current:



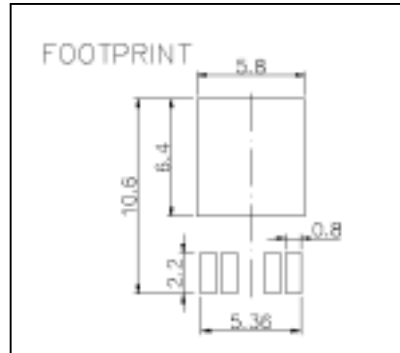
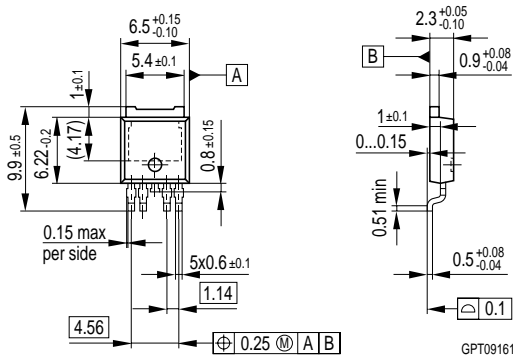
¹⁰⁾ This range for the current sense ratio refers to all devices. The accuracy of the k_{ILIS} can be raised by means of calibration the value of k_{ILIS} for every single device.

Package and Ordering Code

All dimensions in mm

D-Pak-5 Pin: TO-252-5-1

Sales Code	BTS443P
Ordering code	Q67060-S7404-A 2



All metal surfaces tin plated, except area of cut.

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